

Day : Thursday

Date: 3/6/2003

Time: 12:55:07

 PALM INTRANET
Inventor Name Search Result

Your Search was:

Last Name = WU

First Name = CHI-CHUAN

Application#	Patent#	Status	Date Filed	Title	Inventor Name
09474998	6242283	150	12/30/1999	WAFER LEVEL PACKAGING PROCESS OF SEMICONDUCTOR	WU , CHI-CHUAN
09417409	6507098	150	10/13/1999	MULTI-CHIP PACKAGING STRUCTURE	WU , CHI-CHUAN
09832398	6455355	150	04/10/2001	METHOD OF MOUNTING AN EXPOSED-PAD TYPE OF SEMICONDUCTOR DEVICE OVER A PRINTED CIRCUIT BOARD	WU, CHI-CHUAN
09560031	Not Issued	061	04/27/2000	METHOD OF MOUNTING A PASSIVE COMPONENT OVER AN INTEGRATED CIRCUIT PACKAGE SUBSTRATE	WU, CHI-CHUAN
09895553	Not Issued	093	06/28/2001	MULTIPLE STACKED-CHIP PACKAGING STRUCTURE	WU, CHI-CHUAN
09946999	6538321	150	09/05/2001	HEAT SINK WITH COLLAPSE STRUCTURE AND SEMICONDUCTOR PACKAGE WITH HEAT SINK	WU, CHI-CHUAN
09631343	Not Issued	061	08/02/2000	STACKED-DIE PACKAGE STRUCTURE	WU, CHI-CHUAN
09627979	Not Issued	071	07/28/2000	METHOD OF PACKAGING MULTI CHIP MODULE	WU, CHI-CHUAN
09624093	Not Issued	095	07/24/2000	METHOD OF FABRICATING A THIN AND FINE BALL-GRID ARRAY PACKAGE WITH EMBEDDED HEAT SPREADER	WU, CHI-CHUAN
09638989	6281578	150	08/15/2000	MULTI-CHIP MODULE PACKAGE STRUCTURE	WU, CHI-CHUAN
09973151	6472743	150	10/09/2001	SEMICONDUCTOR PACKAGE WITH HEAT DISSIPATING	WU, CHI-CHUAN

				STRUCTURE	
09990160	Not Issued	030	11/20/2001	DCA MEMORY MODULE AND A FABRICATION METHOD THEREOF	WU, CHI-CHUAN
09709224	6281047	150	11/10/2000	METHOD OF SINGULATING A BATCH OF INTEGRATED CIRCUIT PACKAGE UNITS CONSTRUCTED ON A SINGLE MATRIX BASE	WU, CHI-CHUAN
09746793	6414384	150	12/22/2000	PACKAGE STRUCTURE STACKING CHIPS ON FRONT SURFACE AND BACK SURFACE OF SUBSTRATE	WU, CHI-CHUAN
09746819	6507120	150	12/22/2000	FLIP CHIP TYPE QUAD FLAT NON-LEADED PACKAGE	WU, CHI-CHUAN
09699847	Not Issued	071	10/30/2000	STACKED MULTI-CHIP PACKAGE STRUCTURE WITH ON-CHIP INTEGRATION OF PASSIVE COMPONENT	WU, CHI-CHUAN
09757597	Not Issued	041	01/11/2001	PASSIVE ELEMENT SOLDER PAD FREE OF SOLDER BALL	WU, CHI-CHUAN
09718669	Not Issued	041	11/22/2000	TAPE CARRIER PACKAGE STRUCTURE WITH DUMMY PADS AND DUMMY LEADS FOR PACKAGE REINFORCEMENT	WU, CHI-CHUAN
09973358	Not Issued	041	10/09/2001	LEAD FRAME AND FLIP CHIP SEMICONDUCTOR PACKAGE WITH THE SAME	WU, CHI-CHUAN
10026452	Not Issued	071	12/27/2001	SUPER LOW PROFILE PACKAGE WITH STACKED DIES	WU, CHI-CHUAN
09776538	Not Issued	041	02/02/2001	SEMICONDUCTOR PACKAGE FOR MULTI-CHIP STACKS	WU, CHI-CHUAN
09721284	Not Issued	161	11/22/2000	METHOD OF MOUNTING AN EXPOSED-PAD PACKAGE OVER A PRINTED CIRCUIT BOARD	WU, CHI-CHUAN
10060564	Not Issued	061	01/30/2002	SEMICONDUCTOR PACKAGE AND FABRICATION METHOD OF THE SAME	WU, CHI-CHUAN
10196305	Not Issued	030	07/16/2002	FLIP-CHIP SEMICONDUCTOR PACKAGE WITH LEAD FRAME AS CHIP CARRIER AND FABRICATION METHOD THEREOF	WU, CHI-CHUAN

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PALM INTRANET**Inventor Name Search Result**

Your Search was:

Last Name = LO

First Name = RANDY

Application#	Patent#	Status	Date Filed	Title	Inventor Name
08724305	5796570	150	09/19/1996	ELECTROSTATIC DISCHARGE PROTECTION PACKAGE	LO , RANDY H
09235095	6528722	150	01/21/1999	BALL GRID ARRAY SEMICONDUCTOR PACKAGE WITH EXPOSED BASE LAYER	LO , RANDY H. Y.
09474998	6242283	150	12/30/1999	WAFER LEVEL PACKAGING PROCESS OF SEMICONDUCTOR	LO , RANDY H. Y.
08530772	5691567	150	09/19/1995	METHOD AND STRUCTURE FOR ATTACHING A LEAD FRAME TO A HEAT SPREADER/HEAT SLUG STRUCTURE	LO , RANDY H. Y.
09417409	6507098	150	10/13/1999	MULTI-CHIP PACKAGING STRUCTURE	LO , RANDY H. Y.
08891025	6479323	150	07/10/1997	METHOD FOR ATTACHING A LEAD FRAME TO A HEAT SPREADER/HEAT SLUG STRUCTURE	LO , RANDY H. Y.
09047884	5891760	150	03/25/1998	LEAD FRAME WITH ELECTROSTATIC DISCHARGE PROTECTION	LO , RANDY HSIAO-YU
09209634	6166435	150	12/10/1998	FLIP-CHIP BALL GRID ARRAY PACKAGE WITH A HEAT SLUG	LO , RANDY HSIAO-YU
08322769	Not Issued	161	10/13/1994	PLASTIC ENCAPSULATION OF IC DEVICE BY TWO LEVEL EPOXY ENCAPSULATION	LO , RANDY HSIAO-YU
09631343	Not Issued	061	08/02/2000	STACKED-DIE PACKAGE STRUCTURE	LO, RANDY H. Y.

	Issued			PACKAGE STRUCTURE WITH ON-CHIP INTEGRATION OF PASSIVE COMPONENT	
09861425	Not Issued	061	05/18/2001	CIRCUIT PROBING CONTACT PAD FORMED ON A BOND PAD IN A FLIP CHIP PACKAGE	LO, RANDY H.Y.
09545996	6282094	150	04/10/2000	BALL-GRID ARRAY INTEGRATED CIRCUIT PACKAGE WITH AN UNEMBEDDED TYPE OF HEAT-DISSIPATION STRUCTURE AND METHOD OF MANUFACTURING THE SAME	LO, RANDY H.Y.
09746793	6414384	150	12/22/2000	PACKAGE STRUCTURE STACKING CHIPS ON FRONT SURFACE AND BACK SURFACE OF SUBSTRATE	LO, RANDY H.Y.
09699848	Not Issued	041	10/30/2000	CAVITY-DOWN TAPE BALL GRID ARRAY SEMICONDUCTOR PACKAGE WITH GROUNDED HEAT SINK AND METHOD OF FABRICATING THE SAME	LO, RANDY H.Y.
10206720	Not Issued	061	07/26/2002	STRUCTURE OF A MULTI CHIP MODULE HAVING STACKED CHIPS	LO, RANDY H.Y.
09746819	6507120	150	12/22/2000	FLIP CHIP TYPE QUAD FLAT NON-LEADED PACKAGE	LO, RANDY H.Y.
09642319	6258705	150	08/21/2000	METHOD OF FORMING CIRCUIT PROBING CONTACT POINTS ON FINE PITCH PERIPHERAL BOND PADS ON FLIP CHIP	LO, RANDY H.Y.
10039219	Not Issued	041	01/02/2002	SEMICONDUCTOR PACKAGE AND METHOD FOR FABRICATING THE SAME	LO, RANDY H.Y.
09895553	Not Issued	093	06/28/2001	MULTIPLE STACKED-CHIP PACKAGING STRUCTURE	LO, RANDY H.Y.
09915242	Not Issued	030	07/25/2001	MOBILE SELF-CONTAINED VEHICLE WASH	LOCASCIO, RANDY J.
09540998	Not Issued	161	03/31/2000	AMPHOLYTIC POLYMER DISPERSION COMPOSITION AND METHOD OF USE	LOEFFLER, RANDY

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PALM INTRANET
Inventor Name Search Result

Your Search was:

Last Name = LO

First Name = RANDY

Application#	Patent#	Status	Date Filed	Title	Inventor Name
08533118	5617297	150	09/25/1995	ENCAPSULATION FILLER TECHNOLOGY FOR MOLDING ACTIVE ELECTRONICS COMPONENTS SUCH AS IC CARDS OR PCMCIA CARDS	LO , RANDY
09547157	6306682	150	04/11/2000	METHOD OF FABRICATING A BALL GRID ARRAY INTEGRATED CIRCUIT PACKAGE HAVING AN ENCAPSULATING BODY	LO, RANDY H Y
09624093	Not Issued	095	07/24/2000	METHOD OF FABRICATING A THIN AND FINE BALL-GRID ARRAY PACKAGE WITH EMBEDDED HEAT SPREADER	LO, RANDY H Y
09525717	6391758	150	03/14/2000	METHOD OF FORMING SOLDER AREAS OVER A LEAD FRAM	LO, RANDY H. Y.
09561057	6282096	150	04/28/2000	INTERGRATION OF HEAT CONDUCTING APPARATUS AND CHIP CARRIER IN IC PACKAGE	LO, RANDY H. Y.
09577686	6321976	150	05/22/2000	METHOD OF WIRE BONDING FOR SMALL CLEARANCE	LO, RANDY H. Y.
09638989	6281578	150	08/15/2000	MULTI-CHIP MODULE PACKAGE STRUCTURE	LO, RANDY H. Y.
09654814	Not Issued	161	09/05/2000	STRUCTURE OF A MULTI CHIP MODULE HAVING STACKED CHIPS	LO, RANDY H. Y.
09627979	Not Issued	071	07/28/2000	METHOD OF PACKAGING MULTI CHIP MODULE	LO, RANDY H. Y.
09699847	Not	071	10/30/2000	STACKED MULTI-CHIP	LO, RANDY H. Y.